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1. Features

The features of LCD are as follows

- * Display mode : STN/Blue, Transmissive, Negative
- * Drive IC : SPLC502B
- * Display format : 128x64Dots
- * Interface Input Data : 8-Bits
- * Driving Method : 1/65 Duty, 1/9 Bias
- * Viewing Direction : 12 O'clock
- * Backlight : LED (White)
- *Sample NO. : LCM12864B-01S /20100414

2. MECHANICAL SPECIFICATIONS

ltem	Specification	Unit
Module Size	93.8(W) x52.4(H) x 5.5MAX(D)	mm
Number of Dots	128 x 64 Dots	
View display area	72.5(H) x39(V)	Mm
Activity Display Area	66.52(H)x33.24(V)	mm
Dot Size	0.48(H) x0.48(V)	mm
Dot Pitch	0.52(H) x0.52(V)	mm

3. ELECTRICAL SPECIFICATIONS

3-1 ABSOLUTR MAZIMUM RATINGS (Ta = 25 °C)

ltem	Symbol	Star	dard Va	alue	
item	Symbol	Min.	Тур.	Max.	Unit
Supply Voltage For Logic	Vdd – Vss	-0.3	-	3.6	V
Supply Voltage For LCD Drive	V _{op} = Vo – Vss	0.3	-	12	V
Input Voltage	Vin	-0.3	-	VDD+0.3	V
Operating Temp.	Тор	-20	-	+70	°C
Storage Temp.	Tst	-30	-	+80	°C

*. NOTE: The response time will be extremely slow when the operating temperature is around -10 $^{\circ}$ C, and the back ground will become darker at high temperature operating.

3-2 ELECTICAL CHARACTERISTICS

ltem		Symbol	Test Condition	Min.	Тур.	Max.	Unit
Logic supply	Voltage	Vdd - Vss		2.2	3	3.3	V
LCD Dri	ve	V _{OP} =Vo-Vss		8.4	8.7	9.0	V
Input Voltage	"H" Level	V _{IH}	$VDD=3V\pm5\%$	0.8Vdd		Vdd	V
1	"L" Level	V _{IL}		Vss		0.2Vdd	V
Current Cons	umption	IDD		-	1.06	-	mA

3-3. BACKLIGHT

3-3-1. Absolute Maximum Ratings

Item	Symbol	Condition	Min.	Тур.	Max.	Unit
Forward Current	IF				90	mA
Reverse Voltage	VR	Ta = 25 °C 🗼		-	5	V
Power Dissipation	PD			-	306	mW

3-3-2. Electrical-optical Characteristics

ltem	Symbol	Condition	Mi	in.	Ту	γp.	Ма	ax.	Unit
Forward Voltage	VF	lf=90mA Ta = 25 °C	2	.9	3	.1	3.	.4	V
Average Luminous Intensity	I	Ta = 25 °C If=90mA	-	- 200)0	-		cd/m2
Colour Coordinates		IF=90mA	Х	Y	Х	Y	Х	Y	
Colour Coordinates	7	Ta = 25 °C	0.24	0.24	-	-	0.33	0.33	-

The brightness is measured without LCD panel

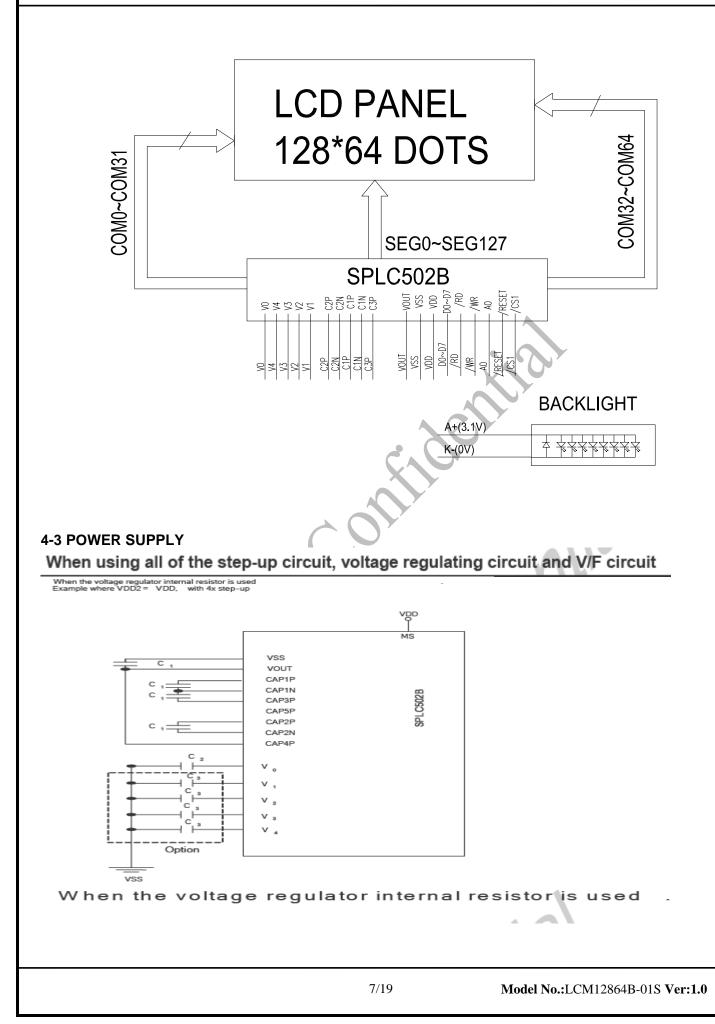
4. TERMINAL FUNCTIONS AND BLOCK DIAGRAM

4-1. INTERFACE PIN FUNCTION DESCRIPTION

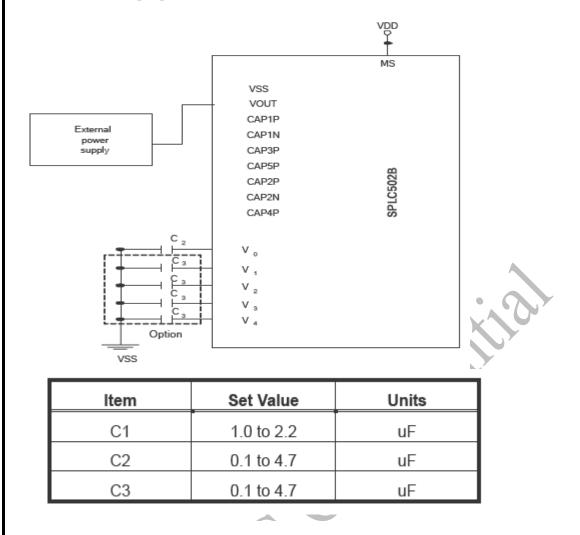
PIN NO.	SYMBOL	FUNCIONS
1	/CS1	Chip enable
2	/RESET	Reset signal
3	A0	Command/data selection
4	/WR	Write signal
5	/RD	Read signal
6~13	D0~D7	Data bus
14	VDD	Power supply (+3.0V)
15	VSS	Power supply (ground)
16	VOUT	DC/DC voltage converter, a capacitor is connected between this terminal and Vss.
17	C3P	DC/DC voltage converter, a capacitor is connected between this terminal and C1P terminal
18	C1N	DC/DC voltage converter, a capacitor is connected between this terminal and C1N terminal
19	C1P	DC/DC voltage converter, a capacitor is connected between this terminal and C1P terminal.
20	C2P	DC/DC voltage converter, a capacitor is connected between this terminal and C2P terminal.
21	C2N	DC/DC voltage converter, a capacitor is connected between this terminal and C2N terminal.
22~26	V1~V4,V0	A multi-level power supply for liquid crystal drive
	A	LED+ 3.1v
	K	LED- 0V

4-2. BLOCK DIAGRAM

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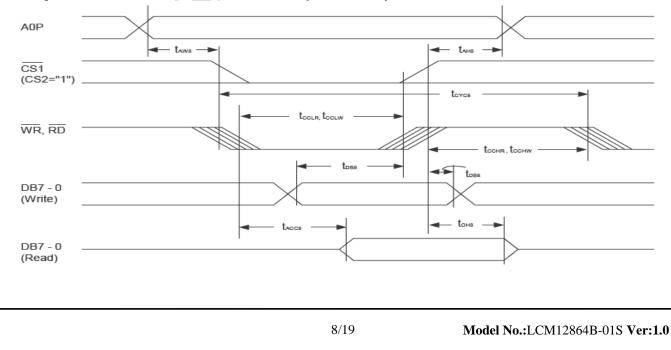


When the voltage regulator internal resistor is used



5. TIMING CHARACTERISTICS

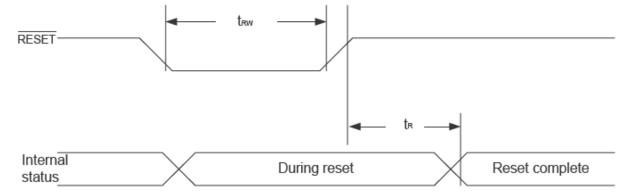
^{5.1} System bus read/write Characteristics (8080serias)



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(VDD = 2.7V to 3.3V, T_A = -20 to 75°C) Rating Signal Symbol 3 8 1 Condition Units ltem Min. Max. Address hold time t_{анв} 0 ns A0P Address setup time 0 t_{aws} ns 400 System cycle time A0P ns t_{cycs} WR 100 Control L pulse width (WR) ns t_{ccuw} 100 ns Control L pulse width (RD) RD t_{CCLR} 100 Control H pulse width (WR) WR _ ns t_{cchw} 100 _ ns Control H pulse width (RD) RD t_{CCHR} 40 Data setup time $t_{\rm DS8}$ ns Address hold time 15 t_{DH8} ns DB7 - 0 RD access time -140 ns t_{ACC8} C_L = 100pF Output disable time 10 100 ns t_{ons}

5.2 The Reset Timing



(VDD = 2.7V to 3.3V, $T_A = -20$ to 75°C)

	c: 1						
ltem	Signal	Symbol	Condition	Min.	Тур.	Max.	Units
Reset time		t _R		-	-	1.0	μs
Reset 'L' pulse width	RES	t _{RW}	-	1.0	-	-	μs

6. INSTRUCTION SET

				(Comm	and C	ode					
Command	A0P	RD	WR	1			DB4	DB3	DB2	DB1	DB0	Function
1). Display ON/OFF	0	1	0	1	0	1	0	1	1	1	0 1	LCD display ON/OFF 0: OFF, 1: ON
2). Display start line set	0	1	0	0	1		Disp	lay sta	art add	ress		Sets the display RAM display start line address
3). Page address set	0	1	0	1	0	1	1	F	^o age a	ddres	s	Sets the display RAM page address
 Column address set upper bit 	0	1	0	o	0	0	1		ost sig	-		Sets the most significant 4 bits of the display RAM column address.
Column address set lower bit	o	1	0	0	0	0	0		east sig	-		Set the least significant 4 bits of the display RAM column address.
5). Status read	0	0	1		Sta	tus		0	0	0	0	Reads the status data
6). Display data write	1	1	0				Write	data				Writes to the display RAM
7). Display data read	1	0	1				Read	data				Reads from the display RAM
8). ADC select	0	1	0	1	0	1	0	0	0	0	0 1	Sets the display RAM address SEG output correspondence 0: normal, 1:reverse
9). Display normal/reverse	0	1	0	1	0	1	0	0	1	1	0	Sets the LCD display normal/ reverse
10). Display all points ON/OFF	0	1	0	1	0	1	0	0	1	0	1 0 1	0: normal, 1:reverse Display all points 0: normal display
11). LCD bias set	0	1	0	1	0	1	0	0	0	1	0	1: all points ON Sets the LCD driver voltage bias ratio
-											1	SPLC502B0:1/9, 1:1/7
12). Read/modify/write	0	1	0	1	1	1	0	0	0	0	0	Column address increment At write: +1 At read: 0
13). End	0	1	0	1	1	1	0	1	1	1	0	Clear read/modify/write
14). Reset	0	1	0	1	1	1	0	0	0	1	0	Internal reset
15). Common output mode select	0	1	0	1	1	0	0	0 1	*	*	*	Select COM output scan direction 0: normal direction, 1: reverse direction
16). Power control set	0	1	0	0	0	1	0	1	Oper	ating r	node	Select internal power supply operating mode
17). V0 voltage regulator internal resistor ratio set	0	1	0	0	0	1	0	0	Res	istor r	atio	Select internal resistor ratio (Rb/Ra) mode
18). Electronic volume	0	1	0	1	0	0	0	0	0	0	1	Set the V0 output voltage electronic
mode set Electronic volume	о	1	0	*	*		Electro	onic v	olume	value		volume register
register set												
Command						and C			0.0-			Function
19). Static indicator	A0P 0	<u>RD</u>	0 WR	DB7 1	DB6 0	DB5 1	DB4 0	DB3 1	DB2 1	DB1 0	DB0 0	0: OFF, 1: ON
ON/OFF Static indicator		-	_	*	*	*	*	*	*	Mo	1	Set the flashing mode
Register set 20). Page Blink	0	1	0	1	1	0	1	0	1	0	1	
Page selection	0	1	0	Р7	P6	P5	Р4	P3	P2	P1	Р0	P7 - 0: 1 - blinking page
21). Driving Mode Set	0	1	0	1	1	0	1	0	0	1	0	0 - no blinking, normal display Set the driving mode register
Mode selection	0	1	0	0	0	0	0	0	0	0	D0	Driving capability (D0): (1)>(0)
22). Power saver												Display OFF and display all points ON compound command
23). NOP	0	1	0	1	1	1	0	0	0	1	1	Command for non-operation
24). Test	0	1	0	1	1 1	1 0	1 1	*	* 1	*	*	Command for IC test. Do not use this command
25). Oscillator Frequency	0	1	0	1	1	1	0	0	1	0	0	20KHz/33KHz (Default)
selection	1										1	16.4KHz/ 27.06KHz

7. QUALITY SPECIFICATIONS 7-1. LCM Appearance and Electric inspection Condition 1. Inspection will be done by placing LCM 30cm away from inspector's eyeballs under normal illumination. Upper Polarizer Metal (Platic) Frame LCD Glass Conductive Rubber-Bottom Polarizer PCB -Backlight Foot (Frame) Coating Epoxy 2. View Angle: with in 45° around perpendicular line. 7-2. Definition **1. COB** 0 PCB 0 Metal (Plastic) Frame [0 LCD 0 0 Ο ଵଵଵଵଵଵଵଵଵଵଵଵଵ 2. Heat Seal LCD Heat Seal 3. TAB and COG LCD Glass LCD Glass IC ITO Terminal Pin Pad IC COG TAB 11/19 Model No.:LCM12864B-01S Ver:1.0

7-3. Sampling Plan and Acceptance

1.Sampling Plan

MIL - STD - 105E (||) ordinary single inspection is used.

THE OID 1001	
2.Acceptance	
Major defect:	AQL = 0.25%
Minor defect:	AQL = 0.65%

7-4. Criteria

1.COB

Defect	Inspection Item	Inspection Standards					
Major	PCB copper flakes peeling off	Any copper flake in viewing Area should be greater than 1.0mm ²	Reject				
Major	Height of coating epoxy	Exceed the dimension of drawing	Reject				
Major	Void or hole of coating epoxy	Expose bonding wire or IC	Reject				
Major	PCB cutting defect	Exceed the dimension of drawing	Reject				
2.SMT							

2.SMT

Defect	Inspection Item	Inspection Standa	ards
Minor	Component marking not readable	C Y	Reject
Minor	Component height	Exceed the dimension Of drawing	Reject
Major	Component solder defect (missing, extra, wrong component or wrong orientation		Reject
Minor	Component position shift x component soldering pad x \rightarrow x x \rightarrow x x \rightarrow x	X < 3/4Z Y > 1/3D	Reject Reject
Minor	Component tilt component	Y > 1/3D	Reject
Minor	Insufficient solder component θ PAD PCB	<i>θ</i> ≤ 20°	Reject

3. Metal (Plastic) Frame

Defect	Inspection Item	Inspection Standards				
Major	Crack / breakage	Any	Reject			
	N		L	Acceptable of Scratch		
		w<0.1mm	Any	Ignore		
		0.1 <u><</u> w<0.2mm	L <u><</u> 5.0mm	2		
Minor	Frame Scratch	0.2 <u><</u> w<0.3mm	L <u><</u> 3.0mm	1		
		w <u>></u> 0.3mm	Any	0		
		Note : 1. Above criteria applicable to scratch lines with distance greater than 5mm. 2. Scratch on the back side of frame (no visible) can be ignored.				
			X	Acceptable of Dents / Pricks		
		Ф <u><</u>	2			
	Frame Dent, Prick	1.0<	⊃ <u><</u> 1.5mm	1		
Minor	$\Phi = \frac{L + W}{2}$	1.5	$mm < \Phi$	0		
	2	Note : 1. Above criteria applicable to any two den / pricks with distance greater than 5mm 2. Dent / prick on the back side of frame (n visible) can be ignored				
Minor	Frame Deformation	Exceed the dimension of drawing				
Minor	Metal Frame Oxidation	Any rust				

4. Flexible Film Connector (FFC)

Defect	Inspection Item	Inspection Standards					
Minor	Tilted soldering Within the angle +5°		Acceptable				
Minor	Uneven solder joint /bump		Reject				
		Expose the conductive line	Reject				
Minor	Hole $\Phi = \frac{L + W}{2}$	Φ > 1.0mm	Reject				
Minor	Position shift $Y \xrightarrow{-\frac{1}{2}} \xrightarrow{-\frac{1}{2}$	Y > 1/3D	Reject				
		X > 1/2Z	Reject				

5. Screw

Defect	Inspection Item	Inspection Standards	
Major	Screw missing/loosen		Reject
Minor	Screw oxidation	Any rust	Reject
Minor	Screw deformation	Difficult to accept screw driver	Reject

6. Heatseal 、TCP 、FPC

Defect	Inspection Item	Inspection Standards	
Major	Scratch expose conductive layer		Reject
Minor	HS Hole $\Phi = \frac{L+W}{2}$	Φ > 0.5mm	Reject
Major	Adhesion strength	Less than the specification	Reject
Minor	Position shift $Y \xrightarrow{-\psi} -\psi$	Y > 1/3D	Reject
Minor		X > 1/2Z	Reject
Major	Conductive line break	Y	Reject

7. LED Backing Protective Film and Others

Defect	Inspection Item	Inspection Standards		
		Acceptable number of units		
	LED dirty, prick	⊕ <u><</u> 0.10mm	Ignore	
		0.10<⊕ <u><</u> 0.15mm	2	
Minor		0.15<⊕ <u><</u> 0.2mm	1	
		Φ >0.2mm	0	
		The distance between any two spots should be \geq Any spot/dot/void outside of viewing area is acce		
Minor	Protective film tilt	Not fully cover LCD	Reject	
Major	COG coating	Not fully cover ITO circuit	Reject	

8. Electric Inspection

	Defect	Inspection Item	Inspection Standards	
Ē	Major	Short		Reject
	Major	Open		Reject

9. Inspection Specification of LCD

Defect	Insp	pect Item				spection		andards		
	* Glass Scratch		W	W <u><</u> 0.03		0.0			V>0.05	
		* Polarizer Scratch	L		L<5			L<3		Any
Minor	Linear Defect	* Fiber and Linear	ACC. NO.			1		1		Reject
		material		L is the length and W is the width of the de					defect	
		* Foreign material	Φ	Φ <u><</u>	0.1	0.1<⊅ <u><</u> 0).15 ().15<⊅ <u><</u> 0.	2	Φ>0.2
		between glass and		3E/	۹/ ۲	2		1		0
	Black Spot	polarizer or glass	NO.	100n	nm	-		•		•
Minor		and glass		A !- 1						
	Pricked	* Polarizer hole or	Note					er of the d efects > 10		-
		protuberance by external force		Dista	ncei	between	wo de	elects > 1	Jmm.	
			Φ		Φ <u><</u>	0.3	0.3	<Φ <u><</u> 0.5	0.	5 <Φ
		transparant foreign material between	ACC. NO.	3EA	A / 10	00mm ²		1		0
	White Spot	glass and glass or	NU.							
Minor	and Bubble in	glass and polarizer			_					
	polarizer	* Air protuberance	Note		Φ is the average diameter of the defect. Distance between two defects > 10mm.				-	
		between polarizer		Dista	nce I	between	wo de	efects > 10)mm.	
		and glass				$\langle \rangle \rangle$	¢ *	1		1
	Segment Defect		Φ	Φ <u><</u> 0	.10	0.10<Φ <u><</u>	<u><</u> 0.20	0.20<⊕ <u><</u>	0.25	Φ> 0. 2
			ACC. NO.	3E/ 100m		2		1		0
Minor				W is more than 1/2 segment width Rejec						
			Note	$\Phi = \frac{L + W}{2}$ Distance between two defect is 10mm						
			Φ	Φ <u><</u> 0	.10	0.10<⊅ <u><</u>	<u>(</u> 0.20	0.20<⊕ <u><</u>	0.25	Φ>0.2
	Protuberant		w	Glu	e	W <u><</u> 1/2 Seg W <u><</u> 0.2		W <u><</u> 1/2 Seg W <u><</u> 0.2 Ign		Ignore
Minor	Segment	$\Phi = (L + W) / 2$	ACC. NO.	3E <i>A</i> 100m	A/ nm ²	2		1		0
			1. Seg	ment				•		
			B	B B <u><</u> 0.4mm 0		0.4 <b<u><1.0mm B>1</b<u>		.0mm		
	Assembly		B-	A B-A<1/2B		B-A<0.2 B-A		<0.25		
Minor	Mis-alignment		Jud	ludge Acceptable Acceptable Acc			Acce	eptable		
			2. Dot	Matrix	K					1
			Deformation>2°				Rejec			
Minor	Stain on LCD Panel Surface		Accept when stains can be wiped lightly with a soft cloth or a similar one. Otherwise, judged according to the above items: "Black spot" and "White Spot"							

8. RELIABILITY

NO.	ltem	Condition	Criterion
1	High Temperature Operating	70℃, 96Hrs	
2	Low Temperature Operating	-20℃, 96Hrs	
3	High Humidity	60℃, 90%RH, 96Hrs	
4	High Temperature Storage	80℃, 96Hrs	
5	Low Temperature Storage	-30℃, 96Hrs	No defect in cosmetic and operational
	Vibration	Random wave	function allowable.
		10 ~ 100Hz	Total current Consumption should
6		Acceleration: 2g	be below double of initial value.
		2 Hrs per direction(X,Y,Z)	
		-20℃ to25℃ to70℃	
7	Thermal Shock	(60Min) (5Min) (60Min)	
		16Cycles	
0		Contract Discharge Voltage: +1 ~ 5kV and -1 ~ -5kV	There will be discharged ten times
8	ESD Testing	Air Discharge Voltage: +1 ~ 8kV and -1 ~ -8kV	at every discharging voltage cycle. The voltage gap is 1kV.

Note: 1) Above conditions are suitable for our company standard products.

2) For restrict products, the test conditions listed as above must be revised.

9. HANDLING PRECAUTION

(1) Mounting Method

The panel of the LCD Module consists of two thin glass plates with polarizers which easily get damaged since the Module is fixed by utilizing fitting holes in the printed circuit board. Extreme care should be taken when handling the LCD Modules.

(2) Caution of LCD handling & cleaning

When cleaning the display surface, use soft cloth with solvent (recommended below) and wipe lightly.

- Isopropyl alcohol
- Ethyl alcohol
- Trichloro trifloro thane

Do not wipe the display surface with dry or hard materials that will damage the polarizer surface. Do not use the following solvent:

- Water- Ketone- Aromatics
- (3) Caution against static charge

The LCD Module use C-MOS LSI drivers, so we recommend that you connect any unused input terminal to VDD or VSS, do not input any signals before power is turned on. And ground your body, Work/assembly table. And assembly equipment to protect against static electricity.

(4) Packaging

- Modules use LCD elements, and must be treated as such. Avoid intense shock and falls from a height.
- To prevent modules from degradation. Do not operate or store them exposed directly to sunshine or high temperature/humidity.
- (5) Caution for operation

- It is indispensable to drive LCD's within the specified voltage limit since the higher voltage than the limit shorten LCD life. An electrochemical reaction due to direct current causes LCD deterioration, Avoid the use of direct current drive.

- Response time will be extremely delayed at lower temperature than the operating temperature range and on the other hand at higher temperature LCD's show dark color in them. However those phenomena do not mean malfunction or out of order with LCD's. Which will come back in the specified operating temperature range.

- If the display area is pushed hard during operation, some font will be abnormally displayed but it resumes normal condition after turning off once.

- A slight dew depositing on terminals is a cause for electro-chemical reaction resulting in terminal open circuit.

Usage under the relative condition of 40°C, 50%RH or less is required.

- (6) Storage
 - In the case of storing for a long period of time (for instance.) For years) for the purpose or replacement use, The following ways are recommended.
 - Storage in a polyethylene bag with sealed so as not to enter fresh air outside in it, And with no desiccant.
 - Placing in a dark place where neither exposure to direct sunlight nor light is. Keeping

temperature in the specified storage temperature range.

- Storing with no touch on polarizer surface by the anything else. (It is recommended to store them as they have been contained in the inner container at the time of delivery)
- (7) Safety
 - It is recommendable to crash damaged or unnecessary LCD into pieces and wash off liquid crystal by using solvents such as acetone and ethanol.

Which should be burned up later.

- When any liquid crystal leaked out of a damaged glass cell comes in contact with your hands, please wash it off well with soap and water.

10. OUTLINE DIMENSION

contraction

